

18 Bit RGB, 8/16-bit parallel, SPI interface



Dimension 52x36x2.2mm 65x43x4.2mm (incl. PCAP)

FEATURES

- 2.0" TFT FULL COLOR
- AACS TECHNOLOGY WITH IPS FOR UNLIMITED VIEWING ANGLE
- 240x320x3 DOTS, CONTROLLER ST7789V
- 800 or 640cd/m² WITHOUT/WITH TOUCHPANEL
- 18-BIT RGB INTERFACE
- 8/16-BIT PARALLEL INTERFACE
- SPI INTERFACE
- INTEGRATED CONTROLLER ST7789V
- SUPPLY VOLTAGE 3.3V
- WIDE TEMPERATURE RANGE (T_{OP} -20°C +70°C)
- OPTIONALLY WITH PCAP AND CONTROLLER GT911

ORDERING CODES

2.0" TFT, 240x320 IPS, 800cd/m²

AS ABOVE BUT WITH OPTICALLY BONDED PCAP

EA TFT020-23AINN EA TFT020-23AITC

ACCESSORY

• ZIF CONNECTOR 0.3mm, BOTTOM CONTACT

EA WF030-39S

Issue 2.2022



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REVISION HISTORY

	Rev.	Page	Description
2018-12-10	1.0	All	First issue
2021-09-12	1.0	6, 33	Count of LED correction

2.0" TFT DISPLAY

With its new 2.0" TFT displays DISPLAY VISIONS launches worldwide the first smaller size displays with high-quality. With its IPS technology these displays provide full viewing angle with all-angle color stability management (AACS). This means that color stays same even when viewing angle is changing.

Display brightness is enormous with $640 \sim 800 \text{cd/m}^2$ and make the displays readable even at direct sunlight. Displays providing many interface modes like standard RGB interface which is suitable even for fast changing display content. The 4-wire SPI interface is perfect for pin saving applications and the 16-bit μC data bus interface enables parallel access to the display.

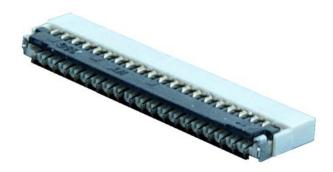
The version EA TFT020-23AITC comes with an optical bonded (OCA) PCAP touch panel. Interface is I²C which makes it easy to read out directly the coordinates.

Connection is simple with a single FPC cable for 39-pin ZIFF connection.

ACCESSORY

The **EA WF030-39S** is the relating ZIF connector for easy and safe connection. Providing connection all in one for:

- Power supply
- TFT Display
- Backlight
- PCAP



Datasheet: https://www.lcd-module.de/eng/pdf/zubehoer/WF030-39S.pdf



ABSOLUTE MAXIMUM RATINGS

The following are maximum values which, if exceeded may cause operation or damage to the unit.

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Power for Circuit Driving	Vcc	-0.3	-	4.6	V	
Power for Circuit Logic	Vt	-0.3	-	Vcc+0.3	V	@25±5°C
Storage Humidity	H _{ST}	10	-		%RH	
Storage Temperature	T _{ST}	-30	-	70	°C	
Operating Ambient Humidity	H _{OP}	10	-		%RH	
Operating Ambient temperature	T_OP	-20	-	70 ¹⁾	°C	

¹⁾ High ambient temperature reduces life time for LED backlight on an increased scale

For more detailed information please refer to the data sheet for ST7789V at

http://www.lcd-module.de/fileadmin/html-seiten/eng/pdf/zubehoer/ST7789V.pdf



ELECTRICAL SPECIFICATION

TFT PANEL

ltem		Symbol	Min	Тур.	Max	Unit	Note
Power for 0	Circuit Driving	VDD	2.5	2.8	3.6	V	
Power For	Circuit Logic	VDDI	1.65	1.8	3.6	V	
Logic Input	Low Voltage	VIL	-0.3	1	0.2VDD	V	
Voltage	High Voltage	VIH	0.8VDD	1	VDD	V	
Logic Output	Low Voltage	VOL	0	-	0.2VDD	V	
Voltage	High Voltage	VOH	0.8VDD	-	-	V	
Power	Black Mode	P _b	T.B.D	T.B.D	T.B.D	mW	
Consumption	Standby Mode	P_{w}	T.B.D	T.B.D	T.B.D	mW	

Note 1: (Unless specified, the ambient temperature $Ta=25\,^{\circ}\!C$)

Note 2: The recommended operating conditions refer to a range in which operation of this product is guaranteed. Should this range is exceeded, the operation cannot be guaranteed even if the values may be without the absolute maximum ratings.



LED BACKLIGHT

Item	Symbol	Min	Тур.	Max	Unit	Note
Backlight driving voltage	VF	23.2	24.0	24.8	V	
Backlight driving current	IF	15	20	25	mA	
Backlight Power Consumption	WBL	-	480	-	mW	
Life Time	-	1	30,000	1		Note 3

Note 1: (Unless specified, the ambient temperature $Ta=25\,^{\circ}\!\text{C}$)

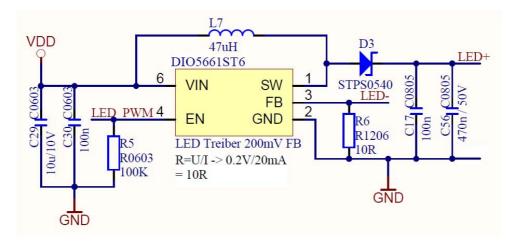
Note 2: The recommended operating conditions refer to a range in which operation of this product is guaranteed. Should this range is exceeded, the operation cannot be guaranteed even if the values may be without the absolute maximum ratings.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.



LED Diagram Circuit

APPLICATION EXAMPLE FOR DRIVING THE LED BACKLIGHT





PCAP TOUCHPANEL

Table 9

Item	Specification	Unit
Touch panel Size	2.8 inches	
Active Area (Sensor)	45.4 (H) x 59.8 (V)	mm
Input type	5 Point multi touch	
Controller	GT911	
Interface mode	I ² C	
Normal mode operating current	typ. 8	mA

TIMING SPECIFICATIONS FOR CTP

I²C Communication

This module provides standard I²C interface for communication. In the system, this module always works in slave mode, all communications are initiated by master, and the baud rate can be up to 400K bps. The definition of I²C timing is as following:

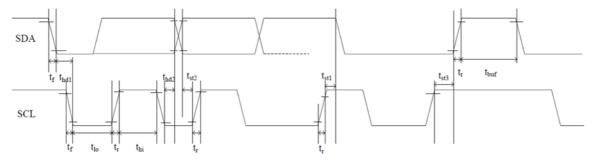


Fig.6 RGB Interface Timing Characteristics

Test condition: 3.3V communication interface, 400Kbps, pull up resistor is 2K ohm

Parameter	Symbol	MIN.	Max.	Unit
SCL low period	t _{lo}	0.9	-	us
SCL high period	t _{hi}	8.0	-	us
SCL setup time for START condition	t _{st1}	0.4	-	us
SCL setup time for STOP condition	t _{st3}	0.4	-	us
SCL hold time for START condition	t _{hd1}	0.3	-	us
SDA setup time	t _{st2}	0.4	-	us
SDA hold time	t _{hd2}	0.4	-	us

This module has 2 sets of slave address 0xBA/0xBB & 0x28/29. Master can control Reset & INT pin to configure the slave address in power on initial state like following:

Power on diagram:

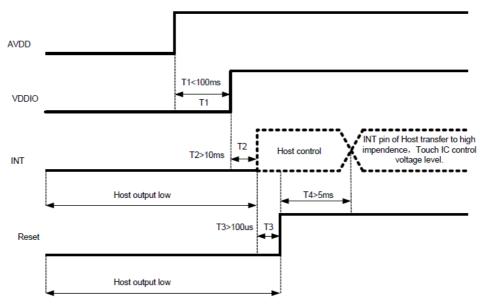


Fig.7 Power on diagram

Timing of setting slave address to 0x28/0x29:

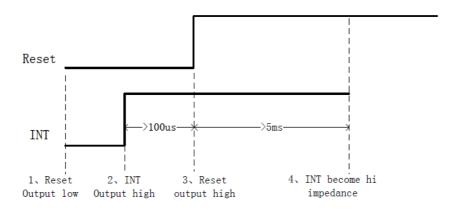


Fig.8(a) Timing of setting slave address

Timing of setting slave address to 0xBA/0xBB:

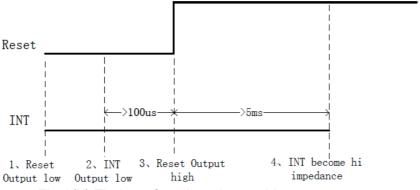


Fig.8(b) Timing of setting slave address



Data Transmission

(ex: slave address is 0xBA/0xBB)

Communication is always initiated by master, A high-to-low transition of SDA with SCL high is a start condition.

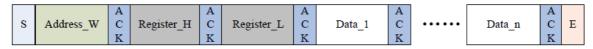
All addressing signal are serially transmitted to and from on bus in 8-bit word. This module sends a "0" to acknowledge when the addressing word is 0xBA/BB (or 0x28/0x29). This happens during the ninth clock cycle. If the slave address is not matched, this module will stay in idle state.

The data words are serially transmitted to and from in 9-bit formation: 8-bit data+1-bit ACK or NACK sent by module. Data changes during SCL low periods & keeps valid during SCL high.

A low-to-high transition of SDA with SCL high is a stop condition.

Write Data to module

(ex: slave address is 0xBA/0xBB)



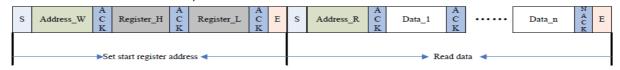
Please check the above figure, master start the communication first, and then sends device address 0XBA preparing for a write operation.

After receiving ACK from module, master sends out 16-bit register address, and then the data word in 8-bit, which is going to be wrote into module.

The address pointer of module will automatically increase one after one byte writing, so master can sequentially write in one operation. When operation finished, master stop the communication.

Read Data from module

(ex: slave address is 0xBA/0xBB)



Please check the above figure, master start the communication first, and then sends device address 0xBA for a write operation.

After receiving ACK from module, master sends out 16-bit register address, to set the address pointer of module. After receiving ACK, master produce start signal once again & send device address 0xBB, then read data word from module in 8-bit.

Module also supports sequential read operation, and the default setting is sequential read mode. Master shall send out ACK after every byte reading successfully but NACK after the last one. Then sends stop signal to finish the communication.



REGISTER INFORMATION OF MODULE

a) Real Time Order

(Write Only)

Addr	Name	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
0x8040	Command	0: read reset3:b 3&4 are	aseline	update 4	4: baselir				

b) Configuration Information

(R/W)

	Config Data	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
0x8047	Config_ Version		Version of the configuration						
0x8048	X Output Max (Low Byte)		Resolution of X axis						
0x8049	X Output Max (High Byte)								
0x804A	Y Output Max (Low Byte)								
0x804B	Y Output Max (High Byte)				Resolution	on of Y axi	5		
0x804C	Touch Number		Res	erved			Touch nu	ımber: 1~5	
0x804D	Module_ Switch1	Res	Reserved Stretch_rank		X2Y	Reser ved	INT trigger 00: risin trigg 01: fallin trigg	g edge er g edge	



							02: low level enquiry		
							03: high level		
							enquiry		
0x804E	Module_ switch2	Reserved							
0x804F	Shake_Count	Res	erved			Finger s	hake count		
0x8050	Filter	First_Filter	Non	_	filtering va		iginal coordinate is 1)		
0x8051	Large_Touch		Nur	mber of tou	ich in large	e area			
0x8052	Noise_ Reduction	Res	erved		Value of		mination (coefficient 0~15)		
0x8053	Screen_ Touch_Level		Thresho	old of touch	grow out	of nothin	g		
0x8054	Screen_ Leave_Level		old of touch	grow out	of nothin	g			
0x8055	Low_Power_ Control	Res	Reserved				Time to low power consumption (0~15s)		
0x8056	Refresh_Rate	Res	erved		Coordinate report rate (Cycle: 5+N ms)				
0x8057	x_threshold			Pas	erved				
0x8058	y_threshold			1765	civeu				
0x8059	X_Speed_Limit			Res	erved				
0x805A	Y_Speed_Limit								
0x805B		Blank area o			Blan		Boarder-bottom		
	Space		ent is 32)		Die		ient is 32)		
0x805C		Blank area o	ent is 32)		Dia		of Boarder-right ient is 32)		
		(COEIIG	on 10 02)		Level o		retch (Stretch X/16		
							itch)		
0x805D	Stretch_Rate	Res	erved		(beta	version i	s valid, published		
					version	n is not)			
0x805E	Stretch_R0	Interval 1 coefficient							
0x805F	Stretch_R1	Interval 2 coefficient							
0x8060	Stretch_R2	Interval 3 coefficient							
0x8061	Stretch_RM		A	II intervals	base num	ber			
0x8062	Drv_GroupA_ Num	All_Dr iving Rese	rved		Driver_(Group_A	number		
0x8063	Drv_GroupB_	Reserved			Driver_0	Group_B	_number		



	Num							
0x8064	Sensor_Num	Se	nsor_Group_B_Nu	mber	Ser	nsor_Grou	up_A_Number	
0x8065	FreqA_factor	[Driver frequency double frequency coefficient of Driver group A GroupA_Frequence = Multiplier factor * baseband					
0x8066	FreqB_factor	[Oriver frequency do GroupB_Fred	_			_	
0x8067	Pannel_ BitFreqL		Baseband of Driver	aroup A\B	1 (1526H7	chasehan	d<14600Hz)	
0x8068	Pannel_ BitFreqH		Dascoand of Driver	group Alb	(1320112	-bascoan	u < 14000112)	
0x8069	Pannel_Sensor _TimeL	Time	e interval of the neil	houring hw	o drivina si	onal /I Init	us) Reserved	
0x806A	Pannel_Sensor _TimeH		o interval of the field	bouring two	o dilving of	griai (Oriii	. doj, reserved.	
0x806B	Pannel_Tx_ Gain		Reserved	ut	Drv_outp _R ears	0:0	nel_DAC_Gain Gain maximum Gain minimum	
0x806C	Pannel_Rx_ Gain	Pann el_PG A_C	Pannel_PGA_R	_			nel_PGA_Gain (8 gears)	
0x806D	Pannel_Dump_ Shift		Reserved		_		efficient of original th power of 2)	
0x806E	Drv_Frame_ Control	Reser ved	Sub	Frame_Dn	vNum		Repeat_Num	
0x806F	NC			Res	served			
0x8070	NC			Res	served			
0x8071	NC			Res	served			
0x8072	Stylus_Tx_ Gain		Undefined	l (invalid	when stylu	s_priority	=0)	
0x8073	Stylus_Rx_ Gain		Undefined	l (invalid	when stylu	s_priority	=0)	
0x8074	Stylus_Dump_ Shift	Magn	ification coefficient	of original	value (The	Nth power	er of 2), Reserved	
0x8075	Stylus_Driver_T ouch_Level		Stylus effe	ctive thres	hold (drivin	ng), Reser	ved	
0x8076	Stylus_Sensor_ Touch_Level	Stylus effective threshold (sensing), Reserved						
0x8077	Stylus_ Control		Pen mode escape time out period (Unit: Sec)					
0x8078	Base_reduce	S-	Style improve quan	ntity		Rese	erved	
0x8079	NC			Res	served			



0x807A	Freq_Hopping_ Start	Frequency hopping start frequency (Unit: 2KHz, 50 means 100KHz)						
0x807B	Freq_Hopping_ End	Free	Frequency hopping stop frequency (Unit: 2KHz, 150 means 300KHz)					
0x807C	Noise_Detect_T imes	_	_Stay_Ti es	Detect_Confirm_Times				
0x807D	Hopping_Flag	Hoppi ng_E n	Res	erved	Detect_Time_Out			
0x807E	Hoppging_ Threshold	Large _.	_Noise_TI	hreshold	Hopping_Hit_Threshold			
0x807F	Noise_ Threshold			П	nreshold of noise level			
0x8080	NC		Reserved					
0x8081	NC				Reserved			
0x8082	Hopping_seg1_ BitFreqL	F						
0x8083	Hopping_seg1_ BitFreqH	riec	quericy no	pping segn	nent band 1 central frequency (for driver A/B)			
0x8084	Hopping_seg1_ Factor		Frequen	cy hopping	segment 1 central frequency coefficient			
0x8085	Hopping_seg2_ BitFreqL	Fred	uency ho	nnina sean	nent band 2 central frequency (for driver A/B)			
0x8086	Hopping_seg2_ BitFreqH	1100	doney no	pping cogn	ionic scand 2 donated respectively (for driver 202)			
0x8087	Hopping_seg2_ Factor		Frequen	cy hopping	segment 2 central frequency coefficient			
0x8088	Hopping_seg3_ BitFreqL	Free	ujency bo	nning sean	nent band 3 central frequency (for driver A/B)			
0x8089	Hopping_seg3_ BitFreqH	1160	pucificy 110	pping segn	ioni band 5 central frequency (for driver A/b)			
0x808A	Hopping_seg3_ Factor	Frequency hopping segment 3 central frequency coefficient						
0x808B	Hopping_seg4_ BitFreqL	Frequency hopping segment band 4 central frequency (for driver A/B)						
0x808C	Hopping_seg4_							



	BitFreqH							
0x808D	Hopping_seg4_ Factor	Frequency hopping segmen	nt 4 central	frequency coefficient				
0x808E	Hopping_seg5_ BitFreqL	Frequency hopping segment bar	nd 5 centra	I frequency (for driver A/B)				
0x808F	Hopping_seg5_ BitFreqH	r requerity hopping segment bar	, , , , , , , , , , , , , , , , , , , ,					
0x8090	Hopping_seg5_ Factor	Frequency hopping segment 5 central frequency coefficient						
0x8091	NC	Re	eserved					
0x8092	NC	Re	eserved					
0x8093	Key 1	Key 1 Position: 0-255 valid (0 mean key when 4 of the						
0x8094	Key 2	Key	2 position					
0x8095	Key 3	Key 3 position						
0x8096	Key 4	Key 4 position						
0x8097	Key_Area	Time limit for long press(1~16 s)	s) Touch valid interval setting: 0-15 valid					
0x8098	Key_Touch_Lev el	Key threshold of touch key						
0x8099	Key_Leave_Lev el	Key threshold of touch key						
0x809A	Key_Sens	KeySens_1(sensitivity coefficient of key 1, same below)		KeySens_2				
0x809B	Key_Sens	KeySens_3		KeySens_4				
0x809C	Key_Restrain	Finger from screen left after inhibition of key time(Unit:100ms,0 means 600ms)		pendent button pro key parameters				
0x809D	NC	Re	eserved					
0x809E	NC	Re	eserved					
0x809F	NC	Re	eserved					
0x80A0	NC	Re	eserved					
0x80A1	NC	Re	eserved					
0x80A2	Proximity_Drv_ Select	Drv_Start_Ch (start channel of driving direction) Drv_End_Ch (End channel)						
0x80A3	Proximity_ Sens_Select	Sens_Start_Ch (start channel of s direction)	Sens_End_Ch (End channel)					
0x80A4	Proximity_ Touch_Level	Proximity effective threshold value						
0x80A5	Proximity_ Leave_Level	Proximity ineffe	ctive threst	hold value				



0x80A6	Proximity_Samp le_Add_Times	Frequency multification of proximity sensing channel.
0x80A7	Proximity_Samp le_Dec_ValL	Sample value minus this value (16 bit), and accumulate, low byte.
0x80A8	Proximity_Samp le_Dec_ValH	Sample value minus this value (16 bit), and accumulate, high byte.
0x80A9	Proximity_Leav e_Shake_Count	exit proximity jitter count
0x80AA	Self_Cap_Tx_g ain	self-capacitance sends gains
0x80AB	Self_Cap_Rx_g ain	self-capacitance receive gains
0x80AC	Self_Cap_Dump _Shift	Magnification coefficient of original value of self-capacitance (The Nth power of 2)
0x80AD	SCap_Diff_Up_ Level_Drv	Self capacitance suppress floating rising threshold (driving direction)
0x80AE	Scap_Merge_T ouch_Level_Drv	Self-capacitance Touch Level (driving direction)
0x80AF	SCap_Pulse_Ti meL	Self-capacitance sampling time (low byte)
0x80B0	SCap_Pulse_Ti meH	Self-capacitance sampling time (high byte)
0x80B1	SCap_Diff_Up_ Level_Sen	Self capacitance suppress floating rising threshold (sensing direction)
0x80B2	Scap_Merge_T ouch_Level_Se n	Self-capacitance Touch Level (sensing direction)
0x80B3	NC	Reserved
0x80B4	NC	Reserved
0x80B5	NC	Reserved
0x80B6	NC	Reserved
0x80B7 ~ 0x80C4	Sensor_CH0~ Sensor_CH13	ITO Sensor corresponding chip channel number
0x80C5 ~ 0x80D4	NC	Reserved
0x80D5 ~ 0x80EE	Driver_CH0~ Driver_CH25	ITO Driver corresponding chip channel number
0x80EF ~	NC	Reserved
-	-	



0x80FE							
0x80FF	Config_Chksum	configuration information verify (the complement number of total byte from 0x8047 to 0x80FE)					
0x8100	Config_Fresh	signal of updated configuration (the host writes)					

c) Coordinates Information

Addr	Access	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	
0x8140	R		Product ID (first byte, ASCII)							
0x8141	R		Product ID (second byte, ASCII)							
0x8142	R		Product ID (third byte, ASCII)							
0x8143	R			Produc	t ID (forth b	yte, A	SCII)			
0x8144	R			Firmwar	e version (H	HEX.lo	w byte)		
0x8145	R			Firmware	version (H	EX.hig	h byte)		
0x8146	R			x coordir	nate resoluti	on (lo	w byte)		
0x8147	R			x coordin	ate resolutio	on (hig	gh byte)		
0x8148	R			y coordir	nate resoluti	on (lo	w byte)		
0x8149	R			y coordin	ate resolutio	on (hig	gh byte)		
0x814A	R		Ve	ndor_id (cu	rrent module	option	n inform	nation)		
0x814B	R				Reserve	ed				
0x814C	R				Reserve	d				
0x814D	R				Reserve	ed				
0x814E	RW	buffer	large detect	Reserved		numb	or of to	uch point		
UX014E	INVV	status	large detect	Reserved		Humb	er or to	uch point	•	
0x814F	R				track id	i				
0x8150	R			point 1	x coordinat	te (low	byte)			
0x8151	R			point 1	x coordinat	e (high	byte)			
0x8152	R			point 1	y coordinat	e (low	byte)			
0x8153	R			point 1	y coordinat	e (high	byte)			
0x8154	R			Po	oint 1 size (lo	ow byte	≘)			
0x8155	R			po	int 1 size (hi	gh byt	e)			
0x8156	R				Reserve	d				
0x8157	R				track ic	j				
0x8158	R			point 2	x coordinat	te (low	byte)			
0x8159	R		point 2 x coordinate (high byte)							
0x815A	R		point 2 y coordinate (low byte)							
0x815B	R		point 2 y coordinate (high byte)							
0x815C	R			ро	int 2 size (lo	w byte	e)			
0x815D	R			po	int 2 size (hi	gh byt	e)			
0x815E	R				Reserve	d				

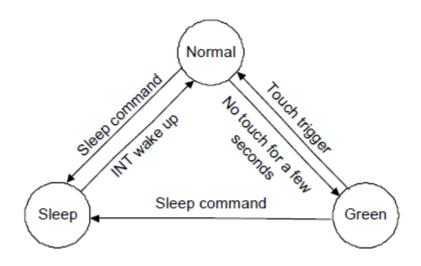


0x815F	R	track id			
0x8160	R	point 3 x coordinate (low byte)			
0x8161	R	point 3 x coordinate (high byte)			
0x8162	R	point 3 y coordinate (low byte)			
0x8163	R	point 3 y coordinate (high byte)			
0x8164	R	point 3 size (low byte)			
0x8165	R	point 3 size (high byte)			
0x8166	R	Reserved			
0x8167	R	track id			
0x8168	R	point 4 x coordinate (low byte)			
0x8169	R	point 4 x coordinate (high byte)			
0x816A	R	point 4 y coordinate (low byte)			
0x816B	R	point 4 y coordinate (high byte)			
0x816C	R	point 4 size (low byte)			
0x816D	R	point 4 size (high byte)			
0x816E	R	Reserved			
0x816F	R	track id			
0x8170	R	point 5 x coordinate (low byte)			
0x8171	R	point 5 x coordinate (high byte)			
0x8172	R	point 5 y coordinate (low byte)			
0x8173	R	point 5 y coordinate (high byte)			
0x8174	R	point 5 size (low byte)			
0x8175	R	point 5 size (high byte)			
0x8176	R	Reserved			
0x8177	R	Reserved			



FUNCTION MODE

Working Mode



a) Normal Mode

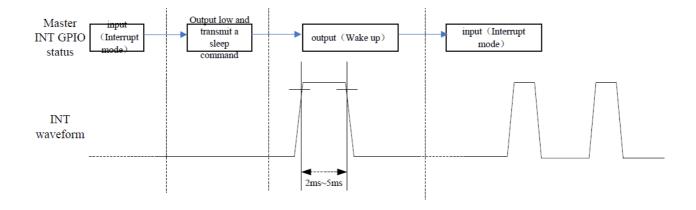
When module is in Normal mode, touch scanning period is about 7ms \sim 10ms depending on the setting. The chip will automatically enter into Green mode if no touch for short time within 0 \sim 15s depending on setting and the step is 1s.

b) Green Mode

In Green mode, the touch scanning cycle is fixed as 40ms. It will automatically enter into Normal mode if any touch is detected.

c) Sleep Mode

For a lower consumption, Master can ask module to enter Sleep mode through I2C command (before the command, please drive low to INT pin). Drive high to the INT pin of module 2~5ms will make module return back to normal mode.



Pulse Calling

Module will inform master to read coordinate information only when touch event happen, in order to lighten the burden of master CPU. The master CPU will set trigger mode by register "INT". "0" means rising edge trigger, in this mode module will output a rising edge hopping in INT, to inform CPU; "1" means falling edge trigger.



Sleep Mode

When the display is turned off or in any circumstance that operation of touch panel is not necessary, master can set module be in Sleep mode through I2C command. The master can wake up module by outputting high to INT pin & keeping 2-5ms.

Frequency Hopping Function

This module has very strong anti-interference hardware, when the driver spectrum of module overlaid with spectrum of noise signal, it can be switch to another frequency by self-adaption frequency hopping mechanism, to avoid interference.

Automatic Calibration

a) Initialization Calibration

Different temperature, humidity and physical structure will affect the sensor's baseline. According to environmental situation module will update the baseline automatically in initialized 200ms.

b) Automatic Temperature Drift

Slow change of temperature, humidity or dust and other environmental factors will also affect the sensor's baseline. module calculates and analyzes historical data, and compare to the current data variation. Base on this, the baseline will be calibration automatically.

For more information, refer to the data sheet GT911:

https://www.lcd-module.de/fileadmin/eng/pdf/zubehoer/GT911%20Datasheet English%2020150625 Rev10.pdf.



OPTICAL SPECIFICATIONS

Optical characteristics are determined after the unit has been 'ON' and stable for approximately 30 minutes in a dark environment at 25 °C. The values specified are at an approximate distance 500mm from the LCD surface at a viewing angle of Φ and θ equal to θ °.

lt one	Or week al		Value		l limit	Nata	
Item	Symbol	Min.	Тур.	Max.	Unit	Note	
1) Contrast Ratio	C/R	640	800	-		FIG.1	
2) Module Luminance	L		800		cd/m²	EA TFT020-23AINN	
2) Module Luminance	L	520	640	-	Cu/III	EA TFT020-23AITC	
3) Response time	T_r+T_f	-	30	-	ms	FIG.2	
	θ_{T}	-	80	-			
1) Viowing Anglo	θ_{B}	-	80	-	Dograd	FIG.3	
4) Viewing Angle	θ_{L}	-	80	-	Degree		
	θ_{R}	-	80	-			
	Wx	0.276	0.296	0.316			
	Wy	0.305	0.325	0.345			
	Rx	-	-	-			
5) Chromaticity	Ry		-	-			
5) Chromaticity	Gx	-	-	-			
	Gy	-	-	-			
	Вх	-	-	-			
	Ву	-	-	-			



MEASUREMENT SYSTEM

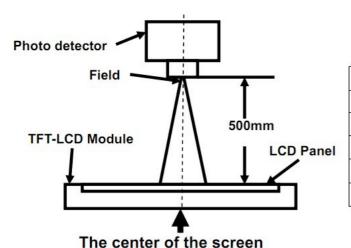
1. Contrast Ratio(CR) is defined mathematically as :

Surface Luminance with all white pixels

Contrast Ratio = ------

Surface Luminance with all black pixels

- 2. Surface luminance is the center point across the LCD surface 500mm from the surface with all pixels displaying white. For more information see FIG 1.
 - 3. Response time is the time required for the display to transition from white to black (Rising Time, Tr) and from black to white (Falling Time, Tf). For additional information see FIG 2.
 - 4. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.



Item	Photo detector	Field
Contrast Ratio		
Luminance	CD 2A	1°
Chromaticity	SR-3A	
Lum Uniformity		
Response Time	BM-7A	2°

FIG. 1 Optical Characteristic Measurement Equipment and Method



The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".

Response Time = Rising Time (T_r) + Falling Time (T_f)

- Rising Time(T_r): Full White 90% \rightarrow Full White 10% Transmittance.
- Falling Time(T_f): Full White 10% \rightarrow Full White 90% Transmittance.

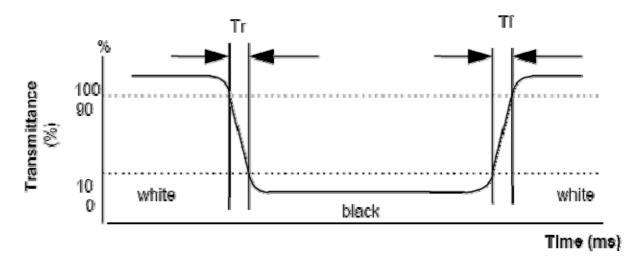


FIG. 2 The definition of Response Time

Use Fig. 1 (Test Procedure) under Measurement System to measure the contrast from the measuring direction specified by the conditions as the following figure.

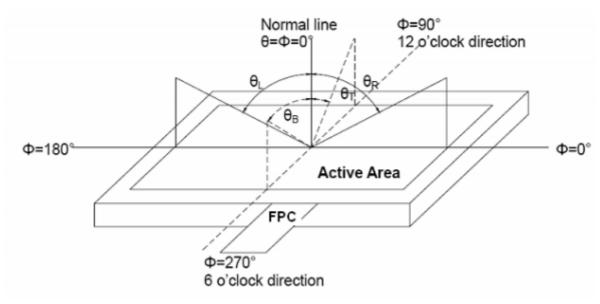
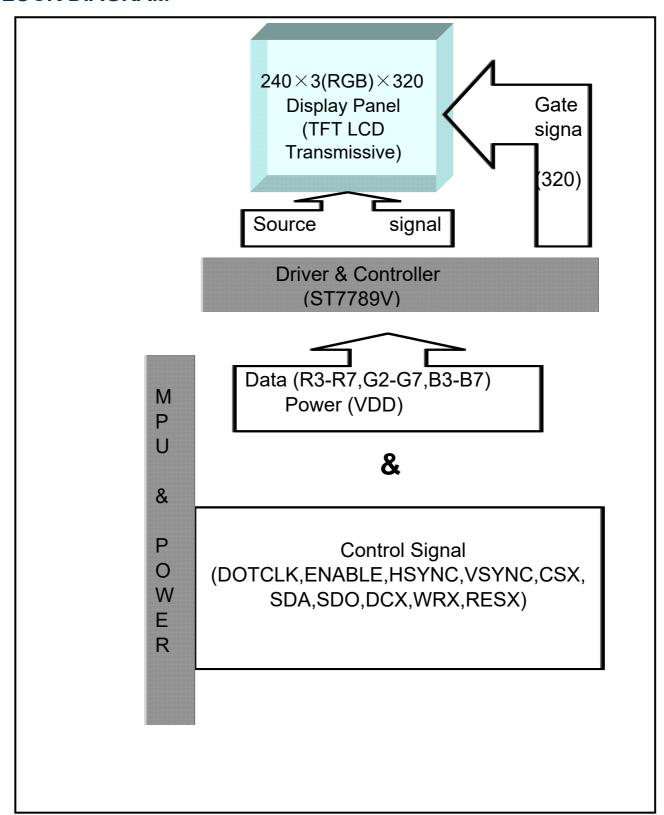


FIG. 3 The definition of Viewing Angle



BLOCK DIAGRAM



PIN DESCRIPTION

Pin Symbol Selected interface (Function) Comment
--



		RGB	8-Bit	16-Bit	SPI	
1	LED-	LED-	LED-	LED-	LED-	LED cathode
2	LED+	LED+	LED+	LED+	LED+	LED anode (typ. 24V)
3	VDD+Touch VDD	VDD	VDD	VDD	VDD	Power input
4	GND+Touch GND	GND	GND	GND	GND	Ground
5	DB0	B2/GND	D0	GND	GND	Data bus
6	DB1	B3	D1	D0	GND	Data bus
7	DB2	B4	D2	D1	GND	Data bus
8	DB3	B5	D3	D2	GND	Data bus
9	DB4	B6	D4	D3	GND	Data bus
10	DB5	B7	D5	D4	GND	Data bus
11	DB6	G2	D6	D5	GND	Data bus
12	DB7	G3	D7	D6	GND	Data bus
13	DB8	G4	GND	D7	GND	Data bus
14	DB9	G5	GND	GND	GND	Data bus
15	DB10	G6	GND	D8	GND	Data bus
16	DB11	G7	GND	D9	GND	Data bus
17	DB12	R2/GND	GND	D10	GND	Data bus
18	DB13	R3	GND	D11	GND	Data bus
19	DB14	R4	GND	D12	GND	Data bus
20	DB15	R5	GND	D13	GND	Data bus
21	DB16	R6	GND	D14	GND	Data bus
22	DB17	R7	GND	D15	GND	Data bus
23	DOTCLK	DOTCLK	GND	GND	GND	Clock signal for RGB interface
24	ENABLE	DE	GND	GND	GND	Data enable signal for RGB interface
25	HSYNC	HSYNC	GND	GND	GND	Horizontal synchronizing
26	VSYNC	VSYNC	GND	GND	GND	Vertical synchronizing
27	TE	DNC	TE	E	DNC	Tearing effect
28	CSX	DNC	CS	CS	CS	L: Chip select for serial interface
29	SDA	SDA	GND	GND	SDA	Serial data in
30	SDO	SDO	GND	GND	SDO	Serial data out
31	DCX	SCL	D/C	D/C	SCL	L: command, H: data /Clock signal for serial interface
32	WRX	D/C	WR	WR	D/C	L: Write enable or L:Command H: Data select pin
33	RESET	RESET	RESET	RESET	RESET	L: Reset for display and touchpanel controller
34	IM1+IM2	VDD	GND	GND	VDD	Interface Mode 1 and 2
35	IM3	VDD	GND	VDD	VDD	Interface Mode 3
36	RDX	GND	RD	RD	GND	L: Read Enable
37	Touch CLK	CLK	CLK	CLK	CLK	Touch serial clock signal
38	Touch SDA	SDA	SDA	SDA	SDA	Touch serial data signal
39	Touch INT	INT	INT	INT	INT	H: Interrupt output

Note 1: RGB mode: B2~B2 internally connected to B7, G0 and G1 internally connected to G7, R0~R2 internally connected to R7

IM3	IM1+IM2	Interface Mode	Data Pins
0	0	Z80 8 Bit parallel	DB[7:0]
0	1	SPI 4 line 8 Bit serial I/F	SDA: in/out
1	0	Z80 16 Bit parallel I/F II	DB[17:10] DB[8:1]
1	1	SPI 4 line 8 Bit serial I/F II	SDA: in SDO: out

Note 2: Interface mode select. IM1+IM2 are connected in parallel, IM0 is fixed to GND

TIMING CHARACTERISTICS (DETAILS REFER TO ST7789V)

Z80/8080 SERIES PARALLEL INTERFACE CHARACTERISTICS: 16/8-BIT BUS

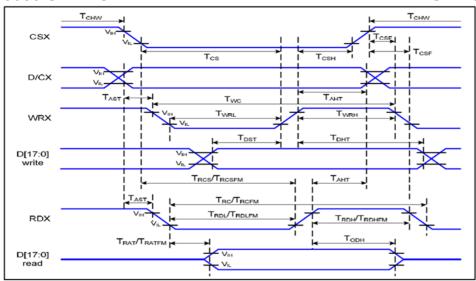


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 $^{\circ}$

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{CS}	Chip select setup time (Write)	15		ns	
csx	T _{RCS}	Chip select setup time (Read ID)	45		ns	_
C37	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{WC}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T_{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	T _{RCFM}	Read cycle (FM)	450		ns	When read from
(FM)	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	frame memory
(FIVI)	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	Traine memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF
	T _{DHT}	Data hold time	10		ns	
	T _{RAT}	Read access time (ID)		40	ns	
	T _{RATFM}	Read access time (FM)		340	ns	
	T _{ODH}	Output disable time	20	80	ns	

SERIAL INTERFACE CHARACTERISTICS (4-LINE SERIAL)

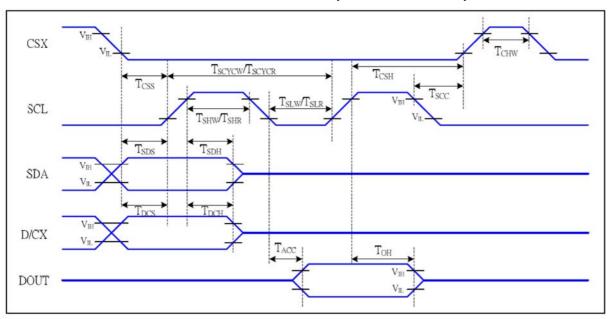


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 $^{\circ}$

Signal	Symbol	Parameter		MAX	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
CSX	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	ram
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	Talli
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	ram
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	Iaili
D/CX	T _{DCS}	D/CX setup time	10		ns	
Diox	T _{DCH}	D/CX hold time	10		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOOT	Тон	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

RGB INTERFACE CHARACTERISTICS

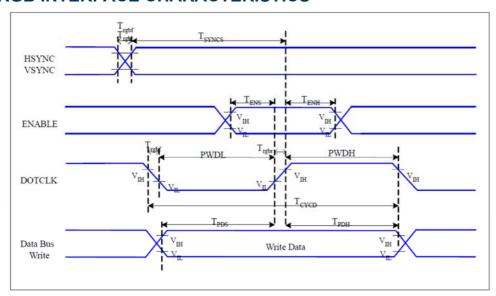


Figure 6 RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 $^{\circ}$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC,	+	VSYNC, HSYNC Setup Time	30	-	ns	
VSYNC	T _{SYNCS}					
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
	T _{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T _{PDS}	PD Data Setup Time	50	-	ns	
	T_PDH	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	25	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
	T _{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	25	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	25	-	ns	
	T _{CYCD}	DOTCLK Cycle Time	55	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	10	ns	
DB	T _{PDS}	PD Data Setup Time	25	-	ns	
	T_PDH	PD Data Hold Time	25	-	ns	

Table 8 6 Bits RGB Interface Timing Characteristics

RESET TIMING

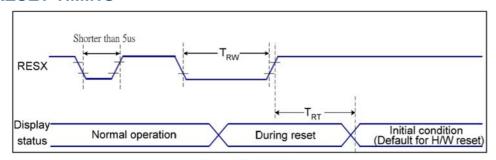


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 ℃

Related Pins	Symbol Parameter		MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TDT	T Reset cancel	-	5 (Note 1, 5)	ms
	IKI		TRT Reset cancel		120 (Note 1, 6, 7)

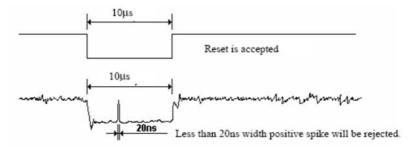
Table 9 Reset Timing

Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to
 registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



RELIABILITY AND INSPECTION STANDARD

No.	Test Item		Test Conditions	Remark	
1 H	High Tomporature	Storage	70°C, 120Hr	Note	
	High Temperature	Operation	60°C, 120Hr	Note	
2	Low Temperature	Storage	-30°C, 120Hr	Note	
2		Operation	-20°C, 120Hr	Note	
3	High Temperature and High Humidity		40°C, 90%RH, 120Hr	Note	
4	Thermal Cycling Test(No operation)		-20C for 30min, 70c for 30 min. 100 cycles. Then test at room temperature after 1 hour	Note	
5	Vibration Test(No c	peration)	Frequency :10~55 HZ; Stroke :1.5 mm;Sweep:10HZ~55HZ~10HZ; 2hours for each direction of X, Y, Z(6 hours for total)		
6	Package Drop Test		Height:60 cm,1 corner, 3 edges, 6 surfaces		
7	Electro Static Dis	charge	±2KV,Human Body Mode, 100pF/1500Ω		

Note: Sample quantity for each test item is 5~10pcs.

Note 4: Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.



INITIALIZATION EXAMPLE

```
WriteComm(0x01):
Delay(200);
//-----//
WriteComm(0x11);
Delay(120); //Delay 120ms
//-----/
WriteComm(0x36); WriteData(0x00);
WriteComm(0x3a); WriteData(0x05);
WriteComm(0x21);
//-----ST7789V Frame rate setting-----//
WriteComm(0xb2); WriteData(0x05); WriteData(0x05); WriteData(0x00); WriteData(0x33);
WriteComm(0xb7); WriteData(0x35);
//-----ST7789V Power setting-----//
WriteComm(0xb8); WriteData(0x2f); WriteData(0x2f);
WriteComm(0xbb); WriteData(0x2B);
WriteComm(0xc0); WriteData(0x2c);
WriteComm(0xc2); WriteData(0x01);
WriteComm(0xc3); WriteData(0x0b);
WriteComm(0xc4); WriteData(0x20);
WriteComm(0xc6); WriteData(0x11);
WriteComm(0xd0); WriteData(0xa4); WriteData(0xa1);
WriteComm(0xe8); WriteData(0x03);
WriteComm(0xe9); WriteData(0x0d); WriteData(0x12); WriteData(0x00);
//-----ST7789V gamma setting-----//
WriteComm(0xe0); WriteData(0xd0); WriteData(0x06); WriteData(0x0b); WriteData(0x0a); WriteData(0x09);
WriteData(0x05); WriteData(0x2e); WriteData(0x43); WriteData(0x44); WriteData(0x09); WriteData(0x16);
WriteData(0x15); WriteData(0x23); WriteData(0x27);
WriteComm(0xel); WriteData(0xd0); WriteData(0x06); WriteData(0x0b); WriteData(0x08);
WriteData(0x06); WriteData(0x2e); WriteData(0x44); WriteData(0x44); WriteData(0x3a); WriteData(0x15);
WriteData(0x15); WriteData(0x23); WriteData(0x26);
//-----Init RGB-Mode-----
WriteComm(0x3A); //Interface Pixel Format
WriteData(0x55); //RGB 65K Colors, Control interface 16bit/pixel
WriteComm(0xB0); //RAM access control
WriteData(0x11); //RGB interface access RAM, Display operation RGB interface
WriteData(0xE0); //16 Bit color format R7 -> R0, MSB first, 18 bit bus width,
WriteComm(0xB1); //RGB interfacecontrol
WriteData(0xEF); //Direct RGB mode, RGB DE Mode, Control pins high active
WriteData(0x08); //VSYNC Back porch setting
WriteData(0x14); //HSYNC Back porch setting
//-----Display on-----
WriteComm(0x11);
Delay(120); //Delay 120ms
WriteComm(0x29);
Delay(100);
```



PRECAUTIONS FOR USING LCD MODULES

HANDING PRECAUTIONS

- (1) The display panel is made of glass and polarizer. As glass is fragile, it tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following:
- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- (9) Do not attempt to disassemble or process the LCD module.
- (10) NC terminal should be open. Do not connect anything.
- (11) If the logic circuit power is off, do not apply the input signals.
- (12) Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

STORAGE PRECAUTIONS

When storing the LCD modules, the following precaution is necessary.



- (1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.
- (2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.
- (3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

OTHERS

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- -Terminal electrode sections.

OUTLINE DIMENSION

